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(12) **United States Design Patent**  
**Okajima et al.**

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(45) **Date of Patent:** **\*\* Jan. 7, 2020**

(54) **COVER OF SEAL CAP FOR REACTION CHAMBER FOR SEMICONDUCTOR MANUFACTURING**

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D813,181 S \* 3/2018 Okajima ..... D13/182  
2014/0302700 A1\* 10/2014 Makinen ..... H01R 13/56  
439/353

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**FOREIGN PATENT DOCUMENTS**

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JP 1579504 S 6/2017

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**OTHER PUBLICATIONS**

U.S. Appl. No. 29/591,907, filed Jan. 25, 2017 by Applicant Hitachi Kokusai Electric Inc., Inventors: Yusaku Okajima, Shuhei Saido and Mika Urushihara.

(\*\*) Term: **15 Years**

\* cited by examiner

(21) Appl. No.: **29/635,319**

*Primary Examiner* — Derrick E Holland

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/101, 118, 122, 133, 156, 162, 182,  
D13/184, 199

CPC ..... H01L 23/02; H01L 23/04; H01L 23/06;  
H01L 23/10; H01L 23/12; H01L 23/13;  
H01L 23/14; H01L 23/42; H01L 21/50;  
H01L 21/563; H01L 21/4817; H01R  
13/20; H01R 13/56; H01R 35/00

See application file for complete search history.

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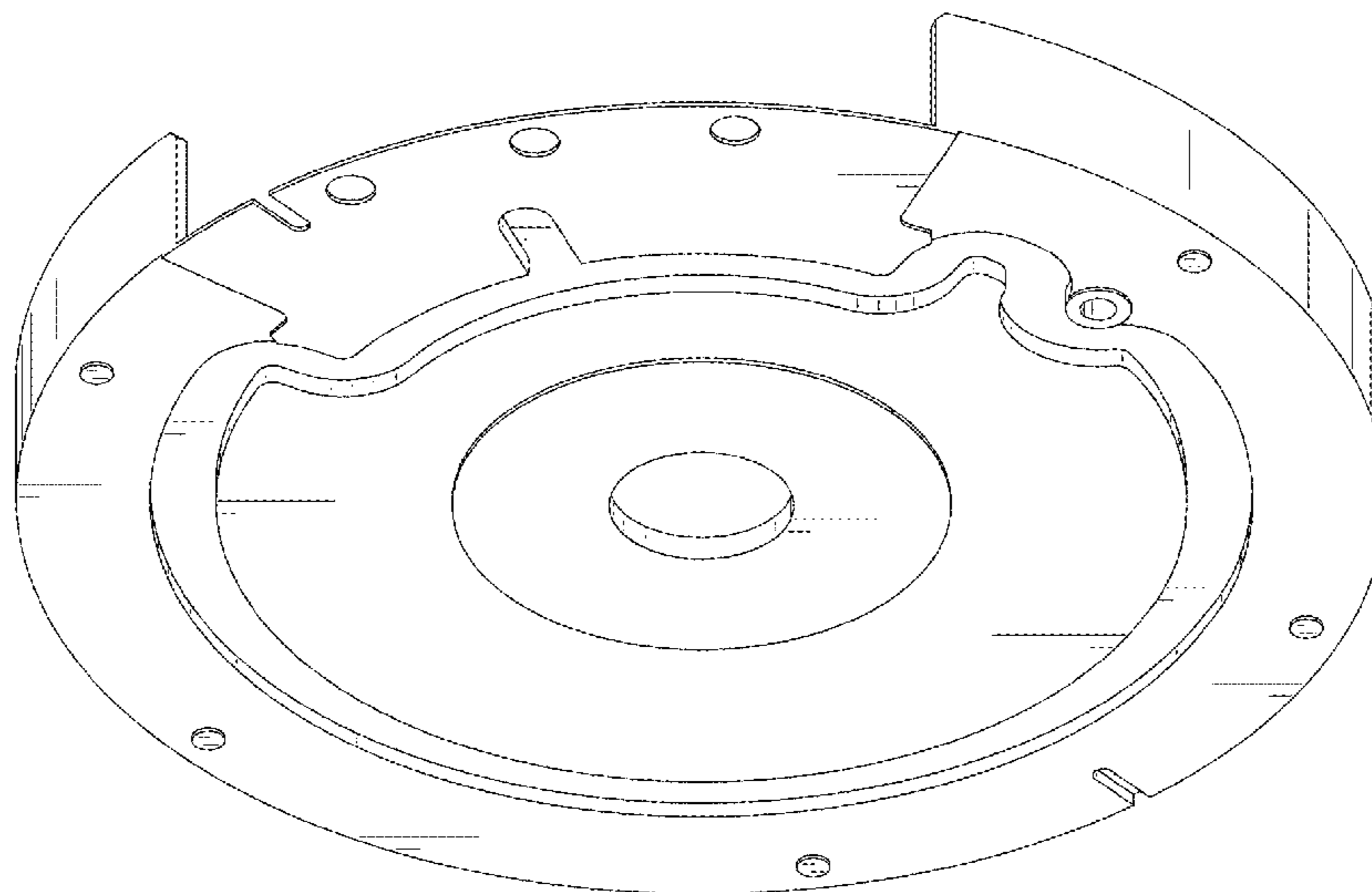
(57) **CLAIM**

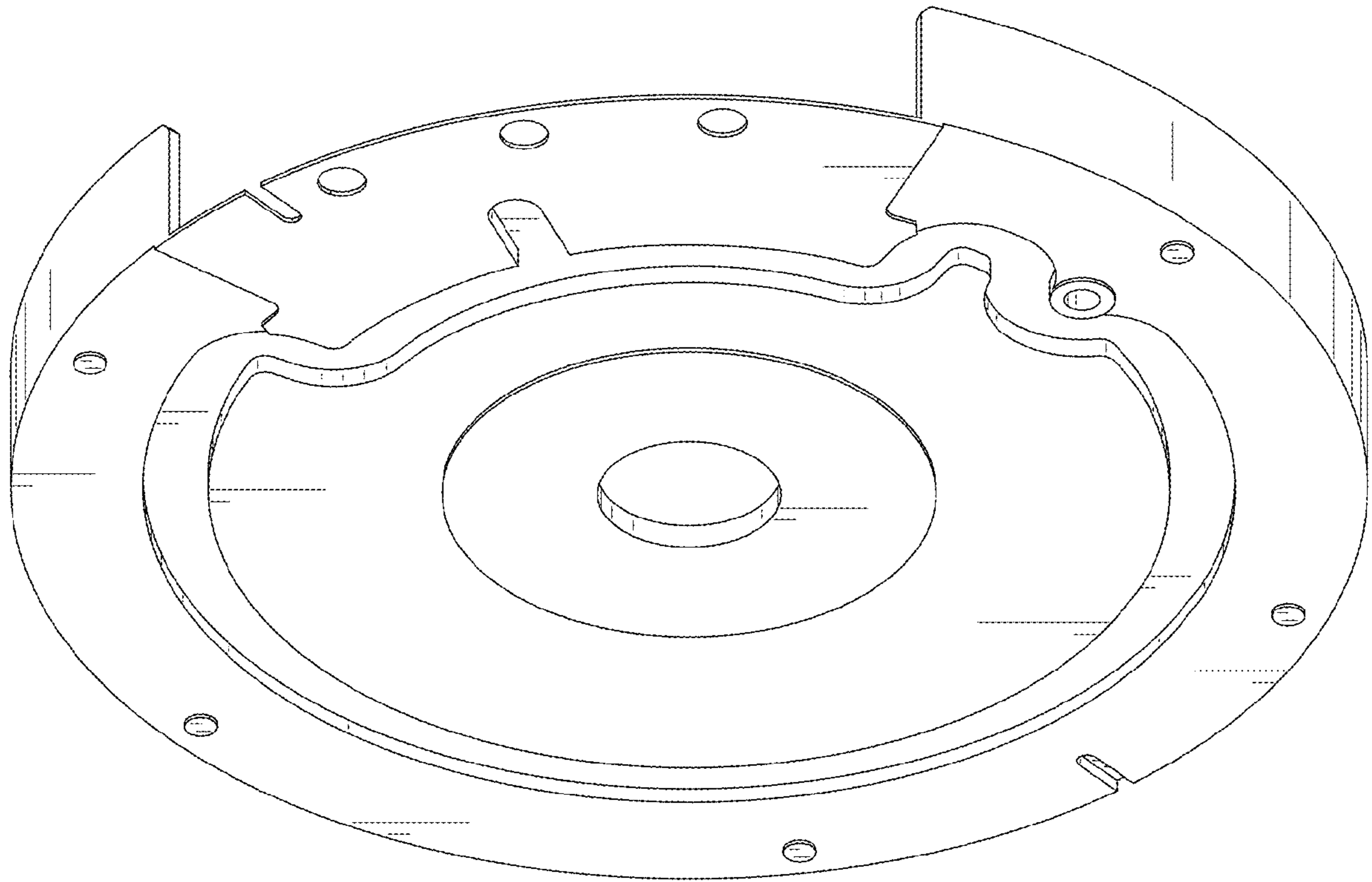
We claim the ornamental design for a cover of seal cap for reaction chamber for semiconductor manufacturing, as shown (and described).

**DESCRIPTION**

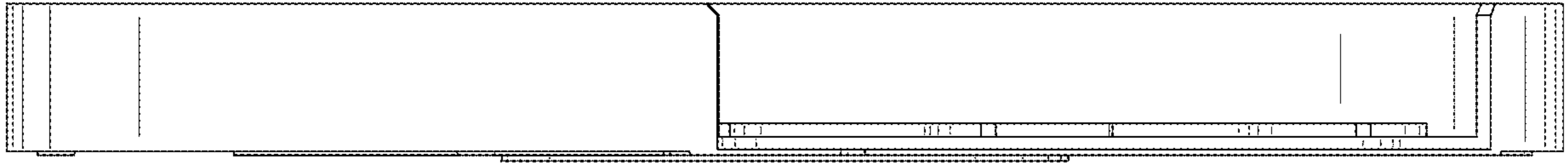
FIG. 1 is a front, bottom and right side perspective view of a cover of seal cap for reaction chamber for semiconductor manufacturing showing our new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a right side elevational view thereof;  
FIG. 5 is a left side elevational view thereof;  
FIG. 6 is a top plan view thereof; and  
FIG. 7 is a bottom plan view thereof.  
FIG. 8 is a cross-sectional view take along line 8-8 in FIG. 6; and,  
FIG. 9 is a cross-sectional view take along line 9-9 in FIG. 7.

**1 Claim, 5 Drawing Sheets**

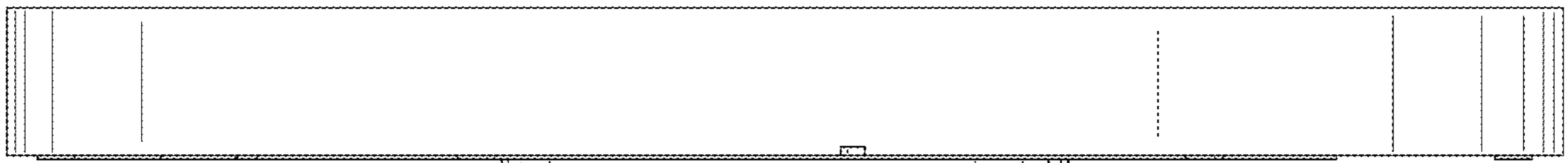




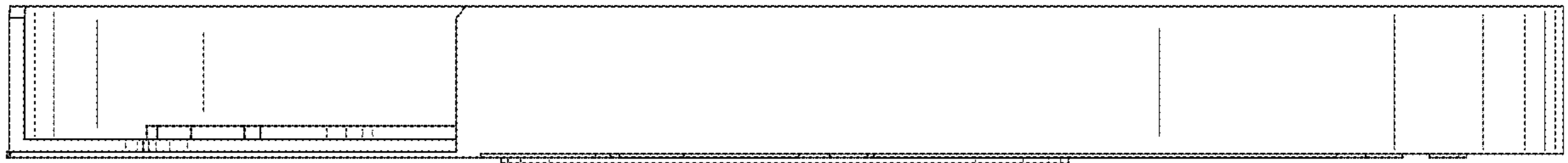
**FIG. 1**



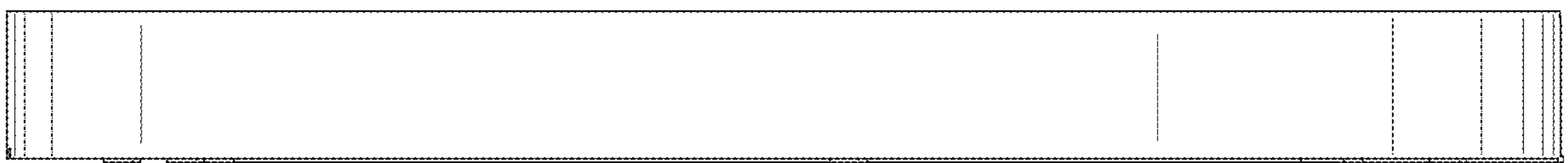
*FIG. 2*



*FIG. 3*



*FIG. 4*



*FIG. 5*

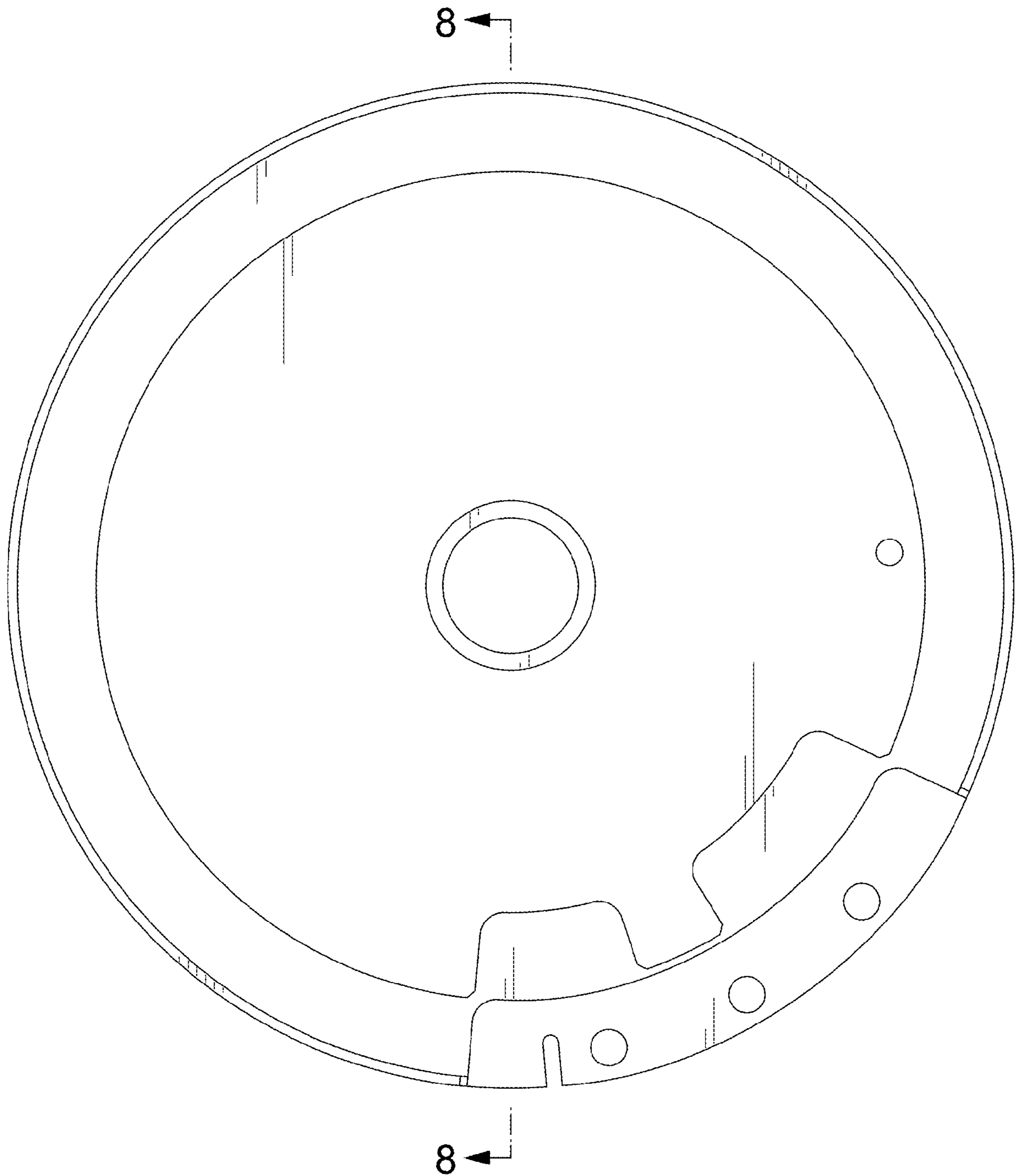


FIG. 6

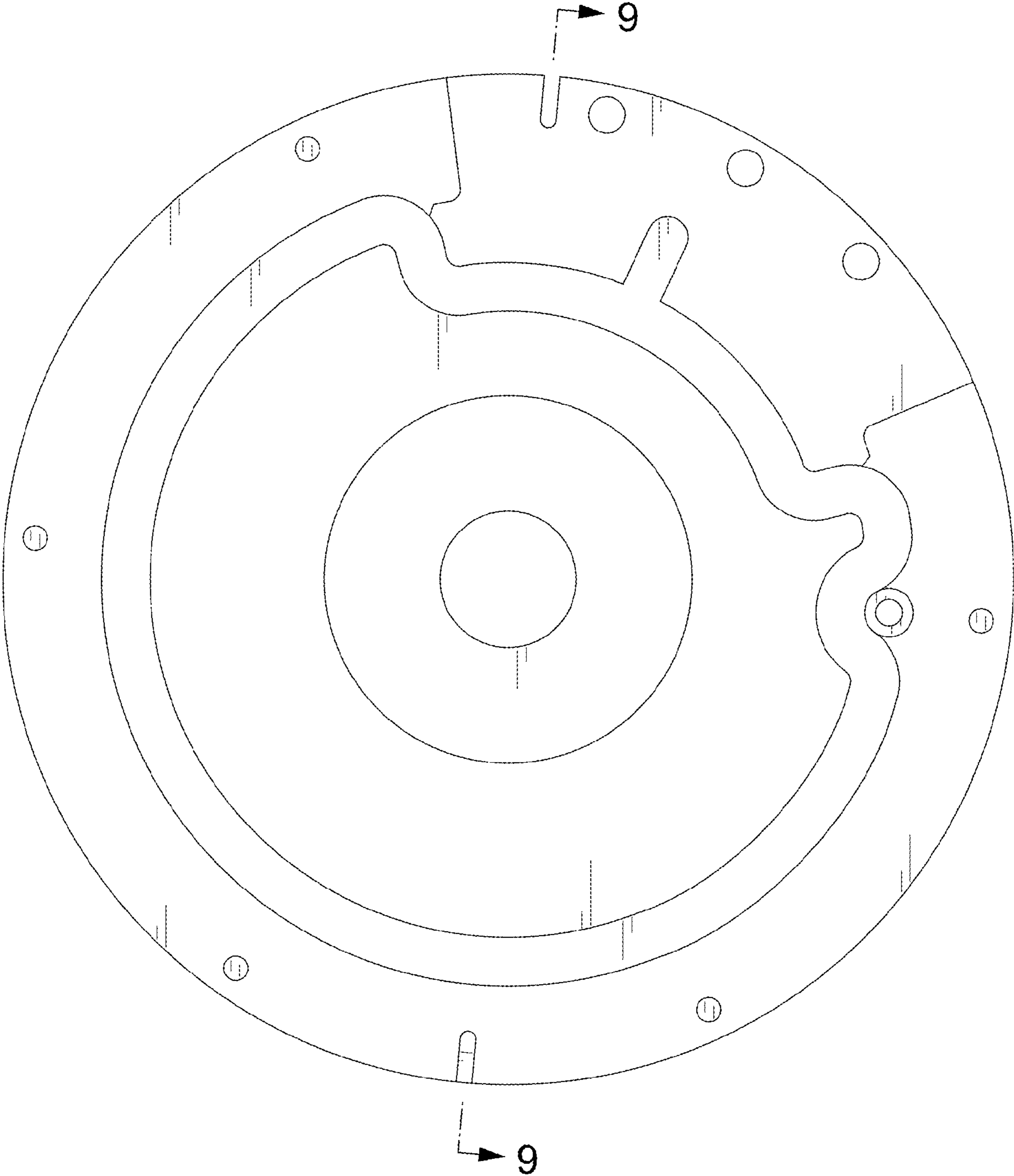
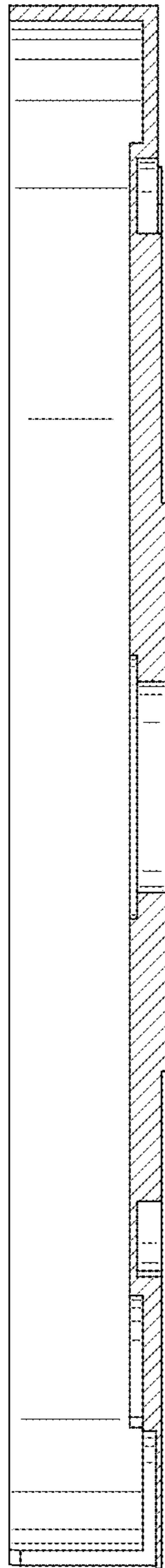
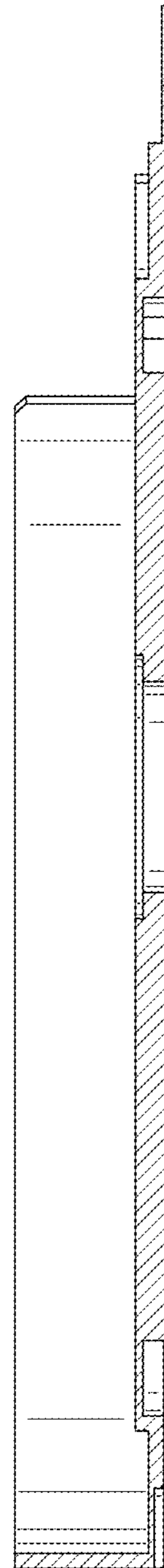


FIG. 7



*FIG. 8*



*FIG. 9*